PCN# : P1C4A
Issue Date : Dec. 29, 2011

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jan. 27, 2012

Expected First Date Code of Changed Product :1201

Last Date for Shipment of Unchanged Product : Jan. 27, 2012

Description of Change (From) :

The current FAN5361UC182X and FPF1003A WLCSP back-end process is performed at two Fairchild sites: bumping is done at South Portland wafer fab, USA and the test and tape&reel are performed at the Penang plant, Malaysia.

Description of Change (To) :

Wafer bumping of FAN5361UC182X and FPF1003A will be performed at Amkor K4, South Korea or Fairchild, South Portland and the Back-End processes for these devices (Test and tape and reel) will be performed at both Amkor T3 plant in Taiwan, R.O.C. and Fairchild Penang plant, Malaysia. All these sites are qualified.

Reason for Change:

We have to increase the flexibility for WLCSP manufacturing capacity. We need to have two viable sources at all times. This is a PCN allowing Fairchild to support our customers with dual source manufacturing.

Affected Product(s):

FAN5361UC182X	FPF1003A	